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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
lumber of I/O	49
Program Memory Size	128KB (128K x 8)
rogram Memory Type	FLASH
EPROM Size	-
AM Size	32K x 8
oltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
ata Converters	A/D 28x10b
Oscillator Type	Internal
perating Temperature	-40°C ~ 105°C (TA)
Nounting Type	Surface Mount
ackage / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
urchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx450f128ht-v-rg

TABLE 1: PIC32MX330/350/370/430/450/470 CONTROLLER FAMILY FEATURES

			0/330/			nappab	le Pe	ripher	als	•										
Device	Pins	Packages	Program Memory (KB) ⁽¹⁾	Data Memory (KB)	Remappable Pins	Timers/Capture/Compare ⁽²⁾	UART	SPI/I ² S	External Interrupts ⁽³⁾	10-bit 1 Msps ADC (Channels)	Analog Comparators	USB On-The-Go (OTG)	СТМU	l²C	PMP	RTCC	DMA Channels (Programmable/Dedicated)	I/O Pins	JTAG	Trace
PIC32MX330F064H	64	QFN, TQFP	64+12	16	37	5/5/5	4	2/2	5	28	2	N	Y	2	Y	Y	4/0	53	Υ	N
PIC32MX330F064L	100 124	TQFP VTLA	64+12	16	54	5/5/5	5	2/2	5	28	2	N	Υ	2	Y	Y	4/0	85	Υ	Υ
PIC32MX350F128H	64	QFN, TQFP	128+12	32	37	5/5/5	4	2/2	5	28	2	N	Υ	2	Υ	Υ	4/0	53	Υ	N
PIC32MX350F128L	100 124	TQFP VTLA	128+12	32	54	5/5/5	5	2/2	5	28	2	N	Υ	2	Υ	Y	4/0	85	Υ	Υ
PIC32MX350F256H	64	QFN, TQFP	256+12	64	37	5/5/5	4	2/2	5	28	2	N	Υ	2	Y	Y	4/0	53	Υ	N
PIC32MX350F256L	100 124	TQFP VTLA	256+12	64	54	5/5/5	5	2/2	5	28	2	N	Y	2	Y	Υ	4/0	85	Y	Υ
PIC32MX370F512H	64	QFN, TQFP	512+12	128	37	5/5/5	4	2/2	5	28	2	N	Υ	2	Y	Y	4/0	53	Υ	N
PIC32MX370F512L	100 124	TQFP VTLA	512+12	128	54	5/5/5	5	2/2	5	28	2	N	Υ	2	Y	Υ	4/0	85	Υ	Υ
PIC32MX430F064H	64	QFN, TQFP	64+12	16	34	5/5/5	4	2/2	5	28	2	Υ	Υ	2	Υ	Υ	4/2	49	Υ	N
PIC32MX430F064L	100 124	TQFP VTLA	64+12	16	51	5/5/5	5	2/2	5	28	2	Υ	Υ	2	Υ	Y	4/2	81	Υ	Υ
PIC32MX450F128H	64	QFN, TQFP	128+12	32	34	5/5/5	4	2/2	5	28	2	Υ	Υ	2	Υ	Υ	4/2	49	Υ	N
PIC32MX450F128HB (see Note 4)	64	QFN, TQFP	128+12	32	34	5/5/5	4	2/2	5	28	2	Υ	Υ	2	Υ	Υ	4/2	49	Υ	N
PIC32MX450F128L	100 124	TQFP VTLA	128+12	32	51	5/5/5	5	2/2	5	28	2	Υ	Υ	2	Υ	Υ	4/2	81	Υ	Υ
PIC32MX450F256H	64	QFN, TQFP	256+12	64	34	5/5/5	4	2/2	5	28	2	Υ	Υ	2	Y	Υ	4/2	49	Υ	N
PIC32MX450F256L	100 124	TQFP VTLA	256+12	64	51	5/5/5	5	2/2	5	28	2	Υ	Υ	2	Υ	Υ	4/2	81	Υ	Υ
PIC32MX470F512H	64	QFN, TQFP	512+12	128	34	5/5/5	4	2/2	5	28	2	Υ	Υ	2	Y	Υ	4/2	49	Y	N
PIC32MX470F512L	100 124	TQFP VTLA	512+12	128	51	5/5/5	5	2/2	5	28	2	Υ	Υ	2	Y	Υ	4/2	81	Y	Υ
PIC32MX470F512LB (see Note 4)	100 124	TQFP VTLA	512+12		51	5/5/5	5	2/2	5	28	2	Υ	Y	2	Y	Y	4/2	81	Y	Υ

Note 1: All devices feature 12 KB of Boot Flash memory.

^{2:} Four out of five timers are remappable.

^{3:} Four out of five external interrupts are remappable.

^{4:} This PIC32 device is targeted to specific audio software packages that are tracked for licensing royalty purposes. All peripherals and electrical characteristics are identical to their corresponding base part numbers

TABLE 7: PIN NAMES FOR 124-PIN DEVICES

PIC32MX470F512L

124-PIN VTLA (BOTTOM VIEW)^(1,2,3,4)
A17
B13
B29
Conductive
Thermal Pad

PIC32MX430F064L
PIC32MX450F128L
PIC32MX450F256L
B1
B56
A51

Α1

Polarity Indicator

A68

A1	No Connect
A2	RG15
A3	Vss
A4	AN23/PMD6/RE6
A5	RPC1/RC1
A6	RPC3/RC3
A7	AN16/C1IND/RPG6/SCK2/PMA5/RG6
A8	AN18/C2IND/RPG8/PMA3/RG8
A9	AN19/C2INC/RPG9/PMA2/RG9
A10	VDD
A11	RPE8/RE8
A12	AN5/C1INA/RPB5/VBUSON/RB5
A13	PGED3/AN3/C2INA/RPB3/RB3
A14	VDD
A15	PGEC1/AN1/RPB1/CTED12/RB1
A16	No Connect
A17	No Connect
A18	No Connect
A19	No Connect
A20	PGEC2/AN6/RPB6/RB6
A21	VREF-/CVREF-/PMA7/RA9
A22	AVDD
A23	AN8/RPB8/CTED10/RB8
A24	CVREFOUT/AN10/RPB10/CTED11/PMA13/RB10
A25	Vss
A26	TCK/CTED2/RA1
A27	RPF12/RF12
A28	AN13/PMA10/RB13
A29	AN15/RPB15/OCFB/CTED6/PMA0/RB15
A30	VDD
A31	RPD15/RD15
A32	RPF5/PMA8/RF5
A33	No Connect
A34	No Connect
A35	USBID/RF3
A36	RPF2/RF2
A37	VBUS

!!	lOI	
	Package Bump #	Full Pin Name
	A38	D-
	A39	SCL2/RA2
	A40	TDI/CTED9/RA4
	A41	VDD
	A42	OSC2/CLKO/RC15
	A43	Vss
	A44	SDA1/RPA15/RA15
	A45	RPD9/RD9
	A46	RPD11/PMCS1/RD11
	A47	SOSCI/RPC13/RC13
	A48	VDD
	A49	No Connect
	A50	No Connect
	A51	No Connect
	A52	AN24/RPD1/RD1
	A53	AN26/RPD3/RD3
	A54	PMD13/RD13
	A55	RPD5/PMRD/RD5
	A56	PMD15/RD7
	A57	No Connect
	A58	No Connect
	A59	VDD
	A60	RPF1/PMD10/RF1
	A61	RPG0/PMD8/RG0
	A62	TRD3/CTED8/RA7
	A63	Vss
	A64	PMD1/RE1
	A65	TRD1/RG12
	A66	AN20/PMD2/RE2
	A67	AN21/PMD4/RE4
	A68	No Connect
	B1	VDD
	B2	AN22/RPE5/PMD5/RE5
	В3	AN27/PMD7/RE7
	B4	RPC2/RC2
	B5	RPC4/CTED7/RC4
l	B6	AN17/C1INC/RPG7/PMA4/RG7
-	1 tortho	railable peripherals and Section 12.2 "Peripheral Din

- Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and Section 12.3 "Peripheral Pin Select" for restrictions.
 - 2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See Section 12.0 "I/O Ports" for more information.
 - Shaded package bumps are 5V tolerant.
 - 4: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

PIC32M	X330/35	0/3/0/4	130/450/	470	
NOTES:					

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- CIN = PIC32 OSC2 Pin Capacitance = ~4-5 pF
- COUT = PIC32 OSC1 Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

```
Crystal manufacturer recommended: C1 = C2 = 15 \ pF
Therefore:
CLOAD = \{([CIN + CI] * [COUT + C2]) / [CIN + CI + C2 + COUT]\} + estimated oscillator PCB stray capacitance
= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5]\} + 2.5 \ pF
= \{([20][20]) / [40]\} + 2.5
= 10 + 2.5 = 12.5 \ pF
Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals "C1" and "C2".
```

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

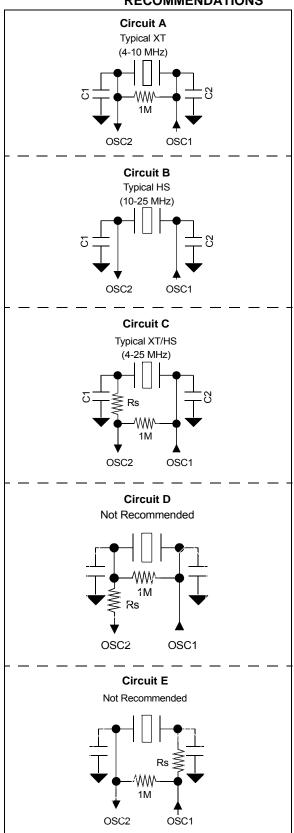
- Select a crystal with a lower "minimum" power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing "ESR" rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator.
 The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit "C" in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~VDD-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 "PICmicro[®] Microcontroller Oscillator Design Guide"
- AN826 "Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"
- AN849 "Basic PICmicro® Oscillator Design"

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



REGISTER 5-1: NVMCON: PROGRAMMING CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31.24	_	1	_	_	_	_	_	_
22:46	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
23:16	_	1	_	_	_	_	_	_
45.0	R/W-0	R/W-0	R-0	R-0	R-0	U-0	U-0	U-0
15:8	WR	WREN	WRERR ⁽¹⁾	LVDERR(1)	LVDSTAT ⁽¹⁾	_	_	_
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
7:0	_	_	_	_		NVMOF	P<3:0>	

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-16 Unimplemented: Read as '0'

bit 15 WR: Write Control bit

This bit is writable when WREN = 1 and the unlock sequence is followed.

1 = Initiate a Flash operation. Hardware clears this bit when the operation completes

0 = Flash operation complete or inactive

bit 14 WREN: Write Enable bit

1 = Enable writes to WR bit and enables LVD circuit

0 = Disable writes to WR bit and disables LVD circuit

This is the only bit in this register reset by a device Reset.

bit 13 **WRERR:** Write Error bit⁽¹⁾

This bit is read-only and is automatically set by hardware.

1 = Program or erase sequence did not complete successfully

0 = Program or erase sequence completed normally

bit 12 LVDERR: Low-Voltage Detect Error bit (LVD circuit must be enabled)⁽¹⁾

This bit is read-only and is automatically set by hardware.

1 = Low-voltage detected (possible data corruption, if WRERR is set)

0 = Voltage level is acceptable for programming

bit 11 LVDSTAT: Low-Voltage Detect Status bit (LVD circuit must be enabled)⁽¹⁾

This bit is read-only and is automatically set, and cleared, by hardware.

1 = Low-voltage event active

0 = Low-voltage event NOT active

bit 10-4 Unimplemented: Read as '0'

bit 3-0 NVMOP<3:0>: NVM Operation bits

These bits are writable when WREN = 0.

1111 = Reserved

•

0111 = Reserved

0110 = No operation

0101 = Program Flash (PFM) erase operation: erases PFM, if all pages are not write-protected

0100 = Page erase operation: erases page selected by NVMADDR, if it is not write-protected

0011 = Row program operation: programs row selected by NVMADDR, if it is not write-protected

0010 = No operation

0001 = Word program operation: programs word selected by NVMADDR, if it is not write-protected

0000 = No operation

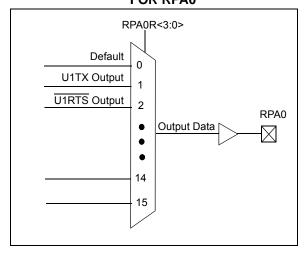
Note 1: This bit is cleared by setting NVMOP = 0000, and initiating a Flash operation (i.e., WR).

12.3.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the peripheral pin select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPnR registers (Register 12-2) are used to control output mapping. Like the [pin name]R registers, each register contains sets of 4 bit fields. The value of the bit field corresponds to one of the peripherals, and that peripheral's output is mapped to the pin (see Table 12-2 and Figure 12-3).

A null output is associated with the output register reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 12-3: EXAMPLE OF MULTIPLEXING OF REMAPPABLE OUTPUT FOR RPA0



12.3.6 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to the peripheral map:

- · Control register lock sequence
- · Configuration bit select lock

12.3.6.1 Control Register Lock

Under normal operation, writes to the RPnR and [pin name]R registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK Configuration bit (CFGCON<13>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear the IOLOCK bit, an unlock sequence must be executed. Refer to **Section 6. "Oscillator"** (DS60001112) in the "PIC32 Family Reference Manual" for details.

12.3.6.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPnR and [pin name]R registers. The IOL1WAY Configuration bit (DEVCFG3<29>) blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure does not execute, and the peripheral pin select control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session.

TABLE 12-2: OUTPUT PIN SELECTION

RPn Port Pin	RPnR SFR	RPnR bits	RPnR Value to Peripheral Selection
RPD2	RPD2R	RPD2R<3:0>	0000 = No Connect
RPG8	RPG8R	RPG8R<3:0>	0001 = U3TX
RPF4	RPF4R	RPF4R<3:0>	0010 = U4RTS 0011 = Reserved
RPD10	RPD10R	RPD10R<3:0>	0110 = Reserved
RPF1	RPF1R	RPF1R<3:0>	0101 = Reserved
RPB9	RPB9R	RPB9R<3:0>	0110 = SDO2
RPB10	RPB10R	RPB10R<3:0>	0111 = Reserved 1000 = Reserved
RPC14	RPC14R	RPC14R<3:0>	1000 - Reserved
RPB5	RPB5R	RPB5R<3:0>	1010 = Reserved
RPC1 ⁽⁴⁾	RPC1R	RPC1R<3:0>	1011 = OC3
RPD14 ⁽⁴⁾	RPD14R	RPD14R<3:0>	1100 = Reserved 1101 = C2OUT
RPG1 ⁽⁴⁾	RPG1R	RPG1R<3:0>	11101 - G2001 1110 = Reserved
RPA14 ⁽⁴⁾	RPA14R	RPA14R<3:0>	1111 = Reserved
RPD3	RPD3R	RPD3R<3:0>	0000 = No Connect
RPG7	RPG7R	RPG7R<3:0>	0001 = U2TX
RPF5	RPF5R	RPF5R<3:0>	0010 = Reserved
RPD11	RPD11R	RPD11R<3:0>	0011 = U1TX 0100 = U5RTS ⁽⁴⁾
RPF0	RPF0R	RPF0R<3:0>	0100 = OSRTS() 0101 = Reserved
RPB1	RPB1R	RPB1R<3:0>	0110 = SDO2
RPE5	RPE5R	RPE5R<3:0>	0111 = Reserved
RPC13	RPC13R	RPC13R<3:0>	1000 = SDO1
RPB3	RPB3R	RPB3R<3:0>	1001 = Reserved
RPF3 ⁽²⁾	RPF3R	RPF3R<3:0>	1010 = Reserved
RPC4 ⁽⁴⁾	RPC4R	RPC4R<3:0>	1011 = OC4 1100 = Reserved
RPD15 ⁽⁴⁾	RPD15R	RPD15R<3:0>	1100 = Reserved
RPG0 ⁽⁴⁾	RPG0R	RPG0R<3:0>	1110 = Reserved
RPA15 ⁽⁴⁾	RPA15R	RPA15R<3:0>	1111 = Reserved

Note 1: This selection is only available on General Purpose devices.

^{2:} This selection is only available on 64-pin General Purpose devices.

^{3:} This selection is only available on 100-pin General Purpose devices.

^{4:} This selection is only available on 100-pin USB and General Purpose devices.

^{5:} This selection is not available on 64-pin USB devices.

TABLE 12-5: PORTC REGISTER MAP FOR PIC32MX330F064L, PIC32MX350F128L, PIC32MX350F256L, PIC32MX370F512L, PIC32MX430F064L, PIC32MX450F128L, PIC32MX450F256L, AND PIC32MX470F512L DEVICES ONLY

w																			
es:		ø								Bits									
Virtual Address (BF88_#)	Register Name ⁽¹⁾	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6210	TRISC	31:16	_		_		I	_	_	_	_	_	_	_	_	_	_	_	0000
0210	TRISC	15:0	TRISC15	TRISC14	TRISC13	TRISC12	1	_	_	_			_	TRISC4	TRISC3	TRISC2	TRISC1	_	xxxx
6220	PORTC	31:16	_	1	_	1	I	_	_	_			_	_	_	-		_	0000
0220	FORTO	15:0	RC15	RC14	RC13	RC12	I	_	_	_			_	RC4	RC3	RC2	RC1	_	xxxx
6230	LATC	31:16	_	1	_	1	I	_	_	_			_	_	_	-		_	0000
0230	LAIC	15:0	LATC15	LATC14	LATC13	LATC12	I	_	_	_			_	LATC4	LATC3	LATC2	LATC1	_	xxxx
6240	ODCC	31:16	_	1	_	1	I	_	_	_			_	_	_	-		_	0000
0240	ODCC	15:0	ODCC15	ODCC14	ODCC13	ODCC12	-	_		_	_	_	_	ODCC4	ODCC3	ODCC2	ODCC1	_	xxxx
6250	CNPUC	31:16	_	1	_	1	I	_	_	_			_	_	_	-		_	0000
0230	CINFOC	15:0	CNPUC15	CNPUC14	CNPUC13	CNPUC12	I	_	_	_			_	CNPUC4	CNPUC3	CNPUC2	CNPUC1	_	xxxx
6260	CNPDC	31:16	_	1	_	1	I	_	_	_			_	_	_	-		_	0000
0200	CINFDC	15:0	CNPDC15	CNPDC14	CNPDC13	CNPDC12	I	_	_	_			_	CNPDC4	CNPDC3	CNPDC2	CNPDC1	_	xxxx
6270	CNCONC	31:16	_	-	_		-	_	_	_	_	_	_	_	_	_	_	_	0000
0270	CNCONC	15:0	ON	1	SIDL	1	I	_	_	_			_	_	_	-		_	0000
6280	CNENC	31:16	_	1		1	I	_	_	_			_	_	_	-		_	0000
0200	CINLING	15:0	CNIEC15	CNIEC14	CNIEC13	CNIEC12	_	_	_	_	_	_	_	CNIEC4	CNIEC3	CNIEC2	CNIEC1	_	xxxx
6200	CNSTATC	31:16	_		_		1	_	_	_	_	_	_	_	_	_	_	_	0000
0290	CINGIAIC	15:0	CNSTATC15	CNSTATC14	CNSTATC13	CNSTATC12	_	_	_	_	_	_	_	CNSTATC4	CNSTATC3	CNSTATC2	CNSTATC1	_	xxxx

Legend

x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See Section 12.2 "CLR, SET, and INV Registers" for more information.

16.1 Control Register

REGISTER 16-1: ICXCON: INPUT CAPTURE 'x' CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
24.04	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31:24	_	_	-	-	_	-	-	_
22.46	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
23:16	_	_	_	_	_	_	_	_
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
15.6	ON ⁽¹⁾	_	SIDL	_	_	_	FEDGE	C32
7.0	R/W-0	R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0
7:0	ICTMR	ICI<	1:0>	ICOV	ICBNE		ICM<2:0>	

Legend:

bit 8

R = Readable bit W = Writable bit U = Unimplemented bit

-n = Bit Value at POR: ('0', '1', x = unknown) P = Programmable bit r = Reserved bit

bit 31-16 Unimplemented: Read as '0'

bit 15 **ON:** Input Capture Module Enable bit (1)

1 = Module is enabled

0 = Disable and reset module, disable clocks, disable interrupt generation and allow SFR modifications

bit 14 **Unimplemented:** Read as '0' bit 13 **SIDL:** Stop in Idle Control bit

1 = Halt in CPU Idle mode

0 = Continue to operate in CPU Idle mode

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **FEDGE:** First Capture Edge Select bit (only used in mode 6, ICM<2:0> = 110)

1 = Capture rising edge first 0 = Capture falling edge first C32: 32-bit Capture Select bit

1 = 32-bit timer resource capture0 = 16-bit timer resource capture

bit 7 ICTMR: Timer Select bit (Does not affect timer selection when C32 (ICxCON<8>) is '1')

0 = Timer3 is the counter source for capture1 = Timer2 is the counter source for capture

bit 6-5 ICI<1:0>: Interrupt Control bits

11 = Interrupt on every fourth capture event
 10 = Interrupt on every third capture event
 01 = Interrupt on every second capture event

00 = Interrupt on every capture event

bit 4 ICOV: Input Capture Overflow Status Flag bit (read-only)

1 = Input capture overflow has occurred0 = No input capture overflow has occurred

bit 3 **ICBNE:** Input Capture Buffer Not Empty Status bit (read-only)

1 = Input capture buffer is not empty; at least one more capture value can be read

0 = Input capture buffer is empty

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 21-1: PMCON: PARALLEL PORT CONTROL REGISTER (CONTINUED)

- bit 3 CS1P: Chip Select 0 Polarity bit⁽²⁾
 - 1 = Active-high (PMCS1)
 - $0 = Active-low (\overline{PMCS1})$
- bit 2 **Unimplemented:** Read as '0'
- bit 1 WRSP: Write Strobe Polarity bit

For Slave Modes and Master mode 2 (MODE<1:0> = 00,01,10):

- 1 = Write strobe active-high (PMWR)
- $0 = Write strobe active-low (\overline{PMWR})$

For Master mode 1 (MODE<1:0> = 11):

- 1 = Enable strobe active-high (PMENB)
- 0 = Enable strobe active-low (PMENB)
- bit 0 RDSP: Read Strobe Polarity bit

For Slave modes and Master mode 2 (MODE<1:0> = 00,01,10):

- 1 = Read Strobe active-high (PMRD)
- 0 = Read Strobe active-low (PMRD)

For Master mode 1 (MODE<1:0> = 11):

- 1 = Read/write strobe active-high (PMRD/PMWR)
- 0 = Read/write strobe active-low (PMRD/PMWR)
- **Note 1:** When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON control bit.
 - 2: These bits have no effect when their corresponding pins are used as address lines.

PIC32IVIX	(330/350	0/3/0/43	30/450/4	170	
NOTES:					

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
31.24	EDG1MOD	EDG1POL		EDG1S	EL<3:0>		EDG2STAT	EDG1STAT
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
23.10	EDG2MOD	EDG2POL		EDG2S	EL<3:0>		_	_
15:0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
15:8	ON	_	CTMUSIDL	TGEN ⁽¹⁾	EDGEN	EDGSEQEN	IDISSEN ⁽²⁾	CTTRIG
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
7:0				IRNG	<1:0>			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31 **EDG1MOD:** Edge 1 Edge Sampling Select bit

1 = Input is edge-sensitive

0 = Input is level-sensitive

bit 30 EDG1POL: Edge 1 Polarity Select bit

1 = Edge 1 programmed for a positive edge response

0 = Edge 1 programmed for a negative edge response

bit 29-26 EDG1SEL<3:0>: Edge 1 Source Select bits

1111 = Reserved

1110 = C2OUT pin is selected

1101 = C1OUT pin is selected

1100 = IC3 Capture Event is selected

1011 = IC2 Capture Event is selected

1010 = IC1 Capture Event is selected

1001 = CTED8 pin is selected

1000 = CTED7 pin is selected

0111 = CTED6 pin is selected

0110 = CTED5 pin is selected

0101 = CTED4 pin is selected

0100 = CTED3 pin is selected

0011 = CTED1 pin is selected

0010 = CTED2 pin is selected

0001 = OC1 Compare Event is selected

0000 = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge 2 Status bit

Indicates the status of Edge 2 and can be written to control edge source

1 = Edge 2 has occurred

0 = Edge 2 has not occurred

- **Note 1:** When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.
 - 2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.
 - 3: Refer to the CTMU Current Source Specifications (Table 31-42) in **Section 31.0** "Electrical Characteristics" for current values.
 - **4:** This bit setting is not available for the CTMU temperature diode.

TABLE 31-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARA	CTERISTICS	3	(unless of	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for Commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +105^{\circ}C$ for V-temp						
Parameter No.	Typical ⁽³⁾	Maximum	Units	Co	onditions					
Operating (Current (IDD)	(1,2)								
DC20	2.5	4	mA		4 MHz					
DC21	6	9	mA	10 M	Hz (Note 4)					
DC22	11	17	mA	20 M	Hz (Note 4)					
DC23	21	32	mA	40 M	Hz (Note 4)					
DC24	30	45	mA	60 M	Hz (Note 4)					
DC25	40	60	mA	(80 MHz					
DC25a	50	75	mA 100 MHz, -40°C ≤ Ta ≤ +85°C							
DC25c	72	84	mA 120 MHz, 0°C ≤ Ta ≤ +70°C							
DC26	100	_	μA +25°C, 3.3V LPRC (31 kHz) (Note 4)							

- **Note 1:** A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.
 - 2: The test conditions for IDD measurements are as follows:
 - Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
 - · OSC2/CLKO is configured as an I/O input pin
 - USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
 - CPU, program Flash, and SRAM data memory are operational, program Flash memory Wait states = 7, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
 - No peripheral modules are operating (ON bit = 0), but the associated PMD bit is clear
 - · WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
 - · All I/O pins are configured as inputs and pulled to Vss
 - MCLR = VDD
 - CPU executing while(1) statement from Flash
 - · RTCC and JTAG are disabled
 - **3:** Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.
 - 4: This parameter is characterized, but not tested in manufacturing.

FIGURE 31-14: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)

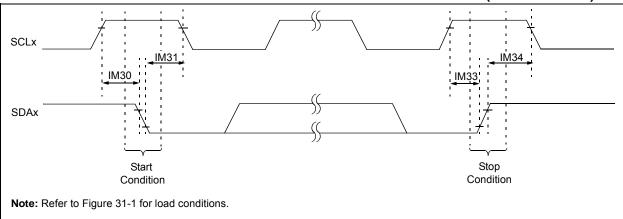


FIGURE 31-15: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)

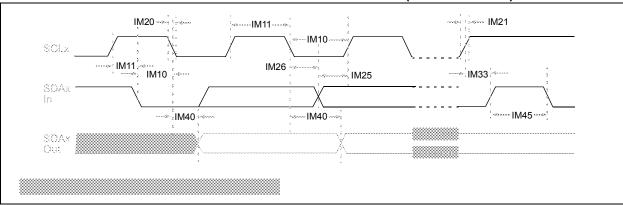


TABLE 31-34: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

AC CHARACTERISTICS							
Param. No.	Symbol	Charact	eristics	Min.	Max.	Units	Conditions
IS34	THD:STO	Stop Condition	100 kHz mode	4000	_	ns	_
		Hold Time	400 kHz mode	600	_	ns	
			1 MHz mode (Note 1)	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	_
			400 kHz mode	0	1000	ns	
			1 MHz mode (Note 1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	_	μS	The amount of time the bus
			400 kHz mode	1.3	_	μS	must be free before a new
			1 MHz mode (Note 1)	0.5	_	μS	transmission can start
IS50	Св	Bus Capacitive Loading		_	400	pF	_

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

PIC32MX330/350/370/430/450/470					
NOTES:					

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.



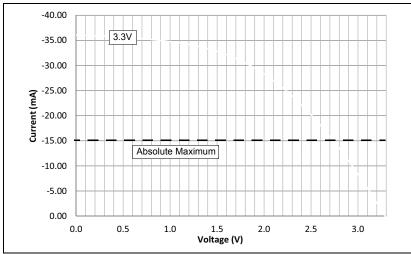


FIGURE 32-3: Vol – 4x DRIVER PINS

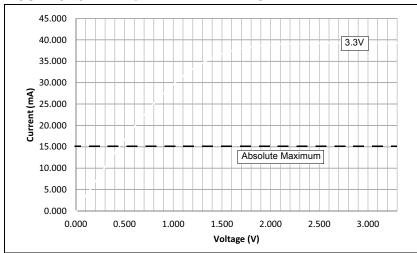


FIGURE 32-2: VoH – 8x DRIVER PINS

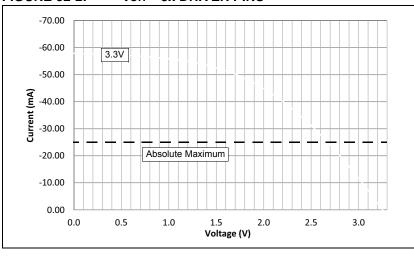
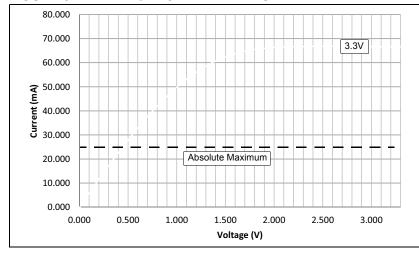


FIGURE 32-4: Vol – 8x DRIVER PINS



33.1 Package Marking Information (Continued)

64-Lead QFN (9x9x0.9 mm) with 5.40x5.40 Exposed Pad



Example



64-Lead QFN (9x9x0.9 mm) with 4.7x4.7 Exposed Pad



Example



124-Lead VTLA (9x9x0.9 mm)



Example



Legend: XX...X Customer-specific information
Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code
Pb-free JEDEC designator for Matte Tin (Sn)
* This package is Pb-free. The Pb-free JEDEC designator (e3)
can be found on the outer packaging for this package.

ote: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

Revision C (October 2013)

This revision includes the following updates, as listed in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section	Update Description				
"32-bit Microcontrollers (up to 512 KB Flash and 128 KB SRAM) with	The Operating Conditions and Core sections were updated in support of 100 MHz (-40°C to +85°C) devices.				
Audio/Graphics/Touch (HMI), USB, and Advanced Analog"	Added Notes 2 and 3 regarding the conductive thermal pad to the 124-pin VTLA pin diagrams.				
2.0 "Guidelines for Getting Started	Updated the recommended minimum connection (see Figure 2-1).				
with 32-bit MCUs"	Added 2.10 "Sosc Design Recommendation".				
20.0 "Parallel Master Port (PMP)"	Updated the Parallel Port Control register, PMCON (see Register 20-1).				
	Updated the Parallel Port Mode register, PMMODE (see Register 20-2).				
	Updated the Parallel Port Pin Enable register, PMAEN (see Register 20-4).				
30.0 "Electrical Characteristics"	Removed Note 4 from the Absolute Maximum Ratings.				
	The maximum frequency for parameter DC5 In Operating MIPS vs. Voltage was changed to 100 MHz (see Table 30-1).				
	Parameter DC25a was added to DC Characteristics: Operating Current (IDD) (see Table 30-5).				
	Parameter DC34c was added to DC Characteristics: Idle Current (IIDLE) (see Table 30-5).				
	Added parameters for PIC32MX370/470 devices and removed Note 5 from DC Characteristics: Power-Down Current (IPD) (see Table 30-7).				
	Updated the Minimum, Typical, and Maximum values and added a reference to Note 3 for parameter DI30 (ICNPU) in DC Characteristics: I/O Pin Input Specifications (see Table 30-8).				
	The SYSCLK values for all required Flash Wait states were updated (see Table 30-13).				
	Added parameter DO50A (Csosc) to the Capacitive Loading Requirements on Output Pins (see Table 30-16).				
	Updated the maximum values for parameter OS10, and the Characteristics definition of parameter OS42 (GM) in the External Clock Timing Characteristics (see Table 30-17).				
31.0 "DC and AC Device Characteristics Graphs"	Updated the IPD, IIDLE, and IDD graphs, and added new graphs for the PIC32MX370/470 devices (see Figure 31-5 through Figure 31-13).				

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